

Summary of Workshop

- ❑ Thank you all !
- ❑ Workshop theme was to “Move beyond the Technical Design Proposal”
 - Looks like we really achieved that goal
- ❑ The success is measured in how well we do in our follow-up

Sensors, Layer 1

- ❑ Goal: Complete comparison ELMA and HPK sensors
 - Goal: Filled out sensor vendor evaluation form
 - Goal: Decide on vendor ELMA, HPK if possible
 - Need information from irradiation studies to make a fair and complete comparison
 - Regina will write-up a summary of the comparison of all electrical characteristics of the sensors by the end of next week
 - Irradiation studies of Layer 1 sensors will be resumed Jan. 20
 - Irradiation studies will be completed 2 weeks later
- ❑ Oxygenation of sensors at ELMA will not be pursued
- ❑ Single- or double-sided polished wafer are acceptable for processing
- ❑ New masks for Layer 1 ELMA sensors ready in 3 weeks
 - Do we need that?
- ❑ Fermilab will pursue use of 'Haggerty' diodes to measure V_{depl} by the end of the year
- ❑ Alice and Marcel will write the list of requirements before production order can be placed by the end of the year

Sensors, Outer Layers

- ❑ Irradiation studies to commence right away
- ❑ Dose profile:
 - 12/13 – 2.0 E12 1 MeV n equivalent
 - 12/17 – 5.0 E12 1 MeV n equivalent
 - 12/20 – 10.0 E12 1 MeV n equivalent
 - 12/24 – 20.0 E12 1 MeV n equivalent
 - Total dose: – 1.12 E14 1 MeV n equivalent
- ❑ Completion of probing and irradiation studies of outer layer sensors by January 20
- ❑ Stony Brook probe site fully operational by second week of January
 - Will receive then certification sensors
- ❑ Regina will study impact of not relying on Cinvestav for probing by mid-January
 - in terms of redistribution of workload
 - impact on labor cost
- ❑ Alice and Marcel will write the list of requirements for production for outer layer sensors by the end of the year

Readout

- ❑ Goals: Agree on mapping scheme for whole detector
 - Has to be deferred until after the shutdown.
 - However, two weeks after the shutdown:
 - » Complete proposal for mapping
 - » Proposal for Interface Board backplanes
 - » Determine need for 2-channel Adapter Cards
 - » Determine the physical size of the Adapter Card
- ❑ Build mock-up of full horseshoe area by mid-February
- ❑ Draftsman needs to be identified to work on horseshoe issues immediately

- ❑ Goal: Decide on physical parameters of adapter card
 - Deferred until mapping is understood
- ❑ AC will allow for dual voltage regulation

- ❑ Goal: Complete design of LV system
 - Done! Have a complete design; need to work out details

Readout

- ❑ 1% Test needs to be given highest priority
 - Install new power supplies
 - Test of Voltage regulation
 - Test of single/dual voltage source
 - Finalize termination of single-ended signals
 - Decide on bypassing of the clocks on Adapter Card or not
 - Decide on actual layout of the Junction Card

 - All Done by April 1 ?

- ❑ Decision to go with 2.5 mm high AVX connector
 - Connectors will be tested by the end of next week to uncover potential problems
 - New cables from Basic will be outfitted with 2.5mm connectors
 - Bill will double check clearances by the end of next week

- ❑ PEEK baseline for cooling tubes
- ❑ Pressure test complete stave and measure silicon-silicon spacing next week
- ❑ Revised QC document for cooling tubes and stave cores by end of next week
- ❑ By January 15:
 - 12 Sensors probed and tested for module assembly
 - All mechanical tests performed on mechanical stave
 - » thermal tests
 - » Goal: Decide on all physical parameters for the stave
 - Start populating first electrical stave (2.5mm AVX)
 - Come up with grounding scheme for staves (Marvin)

- ❑ Manifold and Junction Card positions
 - Fully developed proposal for all locations by February 1
 - » Finalizing cables (analogue, digital 3/12/03, 3/6/03)
 - After finalization of locations, start finalization of cables
 - Try to get resources to start working on mock-up

□ Goals

- Filled out sensor vendor evaluation form
- Decide on vendor ELMA, HPK if possible
- Determine what is needed for PRR for layer1/0 sensors and set time scale for PRR
- First pass at measuring specs of outer layer sensors (?)
- Decide on physical parameters of adapter card
- Decide on low voltage regulation and separate DVDD and AVDD or combined
- Agree on mapping scheme for whole detector
- Complete design of LV system
- Decide on junction card area location
- Decide on stave cores: materials and freeze all dimensions
- Worked out grounding scheme for staves
- Decide on coherent plan for hybrid production and testing
- ...

❑ Database

- Cosmin is given until Jan. 13 to implement all the features needed for sensor (and hybrid) logging
- Joni will start, in collaboration with Cosmin, to work on implementing necessary changes for hybrid tracking
- Cecilia will try to find somebody as backup for Cosmin
 - » Action item for project: need someone with this expertise for the duration

❑ Unpacking software

- Software group will start working on data unpacking code (if someone is available) with hard-coded map to be used in the 1% test